

# ECE 361

## Computer Architecture

### Lecture 1

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# Today's Lecture

## Computer Design

- Levels of abstraction
- Instruction sets and computer architecture

## Architecture design process

## Interfaces

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## Course Structure

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## Technology as an architectural driver

- Evolution of semiconductor and magnetic disk technology
- New technologies replace old
- Industry disruption

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Break
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## Cost and Price

- Semiconductor economics

# Computers, Levels of Abstraction and Architecture

# Computer Architecture's Changing Definition

## 1950s Computer Architecture

- Computer Arithmetic

## 1960s

- Operating system support, especially memory management

## 1970s to mid 1980s Computer Architecture

- Instruction Set Design, especially ISA appropriate for compilers
- Vector processing and shared memory multiprocessors

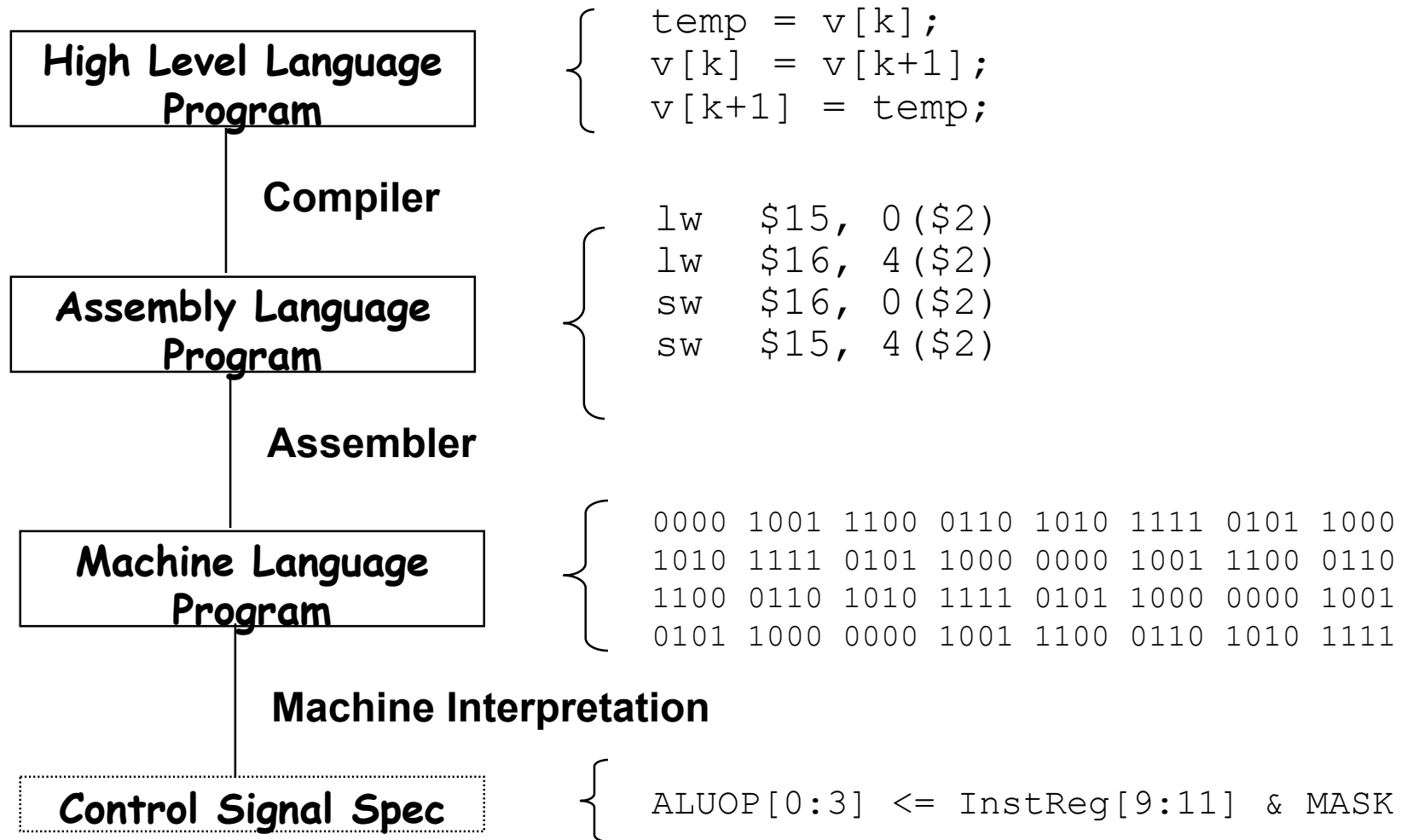
## 1990s Computer Architecture

- Design of CPU, memory system, I/O system, Multi-processors, Networks
- Design for VLSI

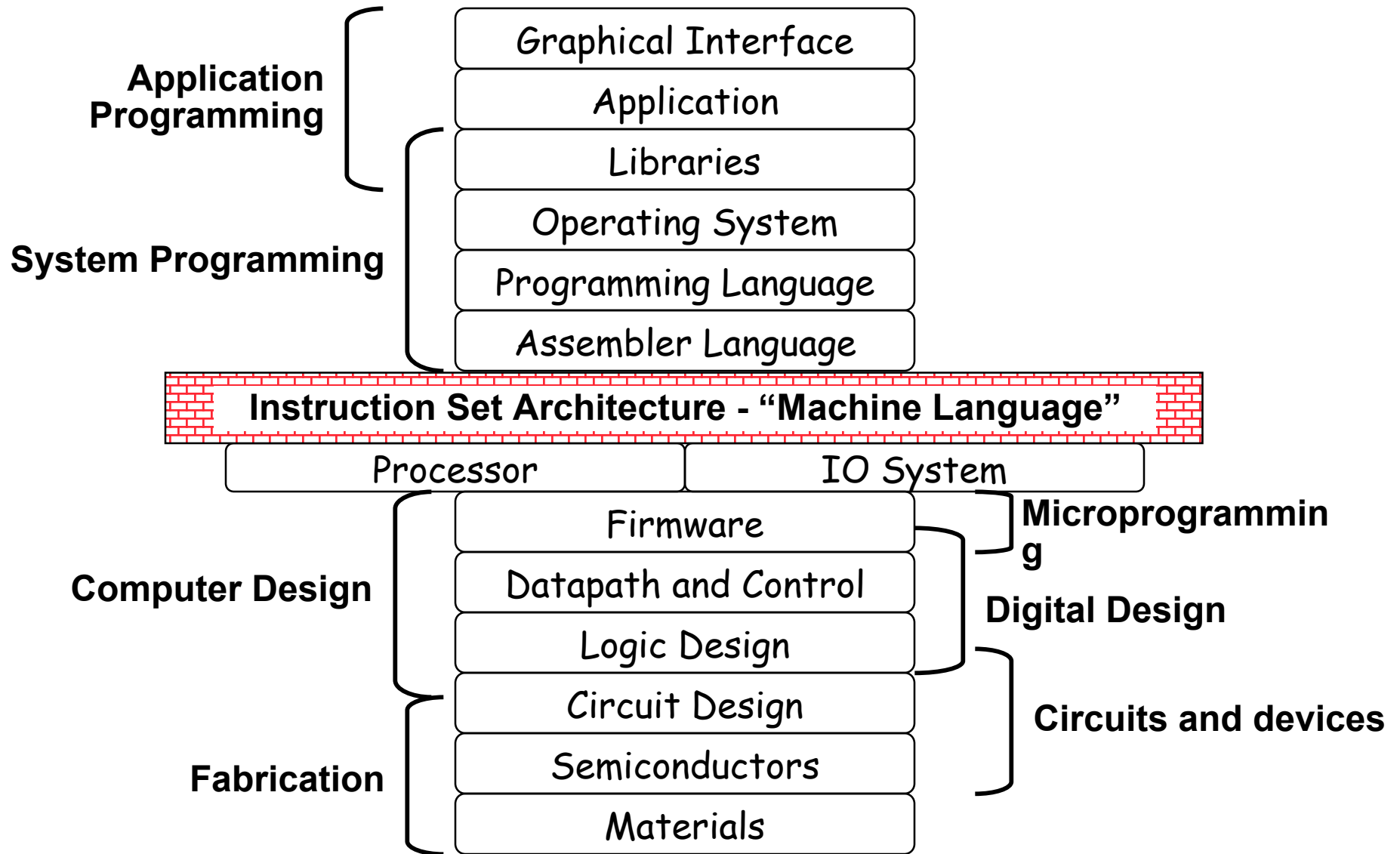
## 2000s Computer Architecture:

- Special purpose architectures, Functionally reconfigurable, Special considerations for low power/mobile processing, highly parallel structures

# Levels of Representation



# Levels of Abstraction



# The Instruction Set: A Critical Interface

Computer Architecture =  
Instruction Set Architecture +  
Machine Organization

## Instruction Set Design

- Machine Language
- Compiler View
- "Computer Architecture"
- "Instruction Set Architecture"

"Building Architect"

software



hardware

This course

## Computer Organization and Design

- Machine Implementation
- Logic Designer's View
- "Processor Architecture"
- "Computer Organization"

"Construction Engineer"

# Instruction Set Architecture

## Data Types

Encoding and representation

## Memory Model

## Program Visible Processor State

General registers

Program counter

Processor status

## Instruction Set

Instructions and formats

Addressing modes

Data structures

## System Model

States

Privilege

Interrupts

IO

## External Interfaces

IO

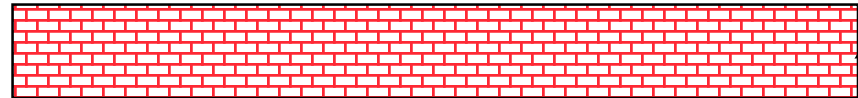
Management

Architecture Reference Manual

Principles of Operation

Programming Guide

...

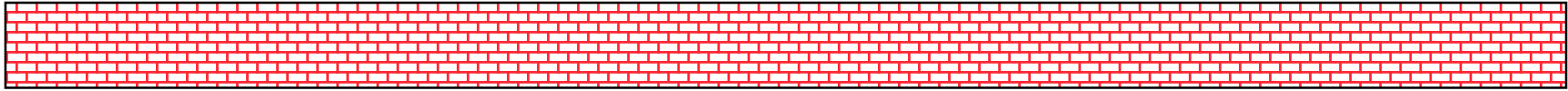


... the attributes of a [computing] system as seen by the programmer, i.e. the conceptual structure and functional behavior, as distinct from the organization of the data flows and controls the logic design, and the physical implementation.

Amdahl, Blaaw, and Brooks, 1964



# Computer Organization



## Capabilities & Performance Characteristics of Principal Functional Units

(e.g., Registers, ALU, Shifters, Memory Management, etc.)

## Ways in which these components are interconnected

- Datapath - nature of information flows and connection of functional units
- Control - logic and means by which such information flow is controlled

## Choreography of functional units to realize the ISA

## Register Transfer Level Description / Microcode

*"Hardware" designer's view includes logic and firmware*

# This Course Focuses on General Purpose Processors

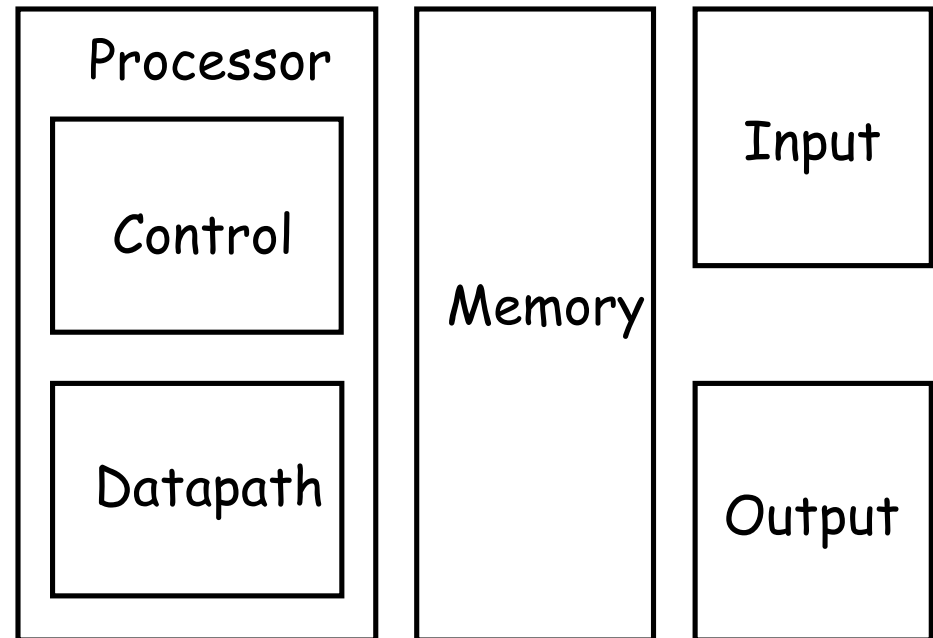
## A general-purpose computer system

- Uses a programmable processor
- Can run “any” application
- Potentially optimized for some class of applications
- Common names: CPU, DSP, NPU, microcontroller, microprocessor

## Unified main memory

- For both programs & data
- Von Neumann computer

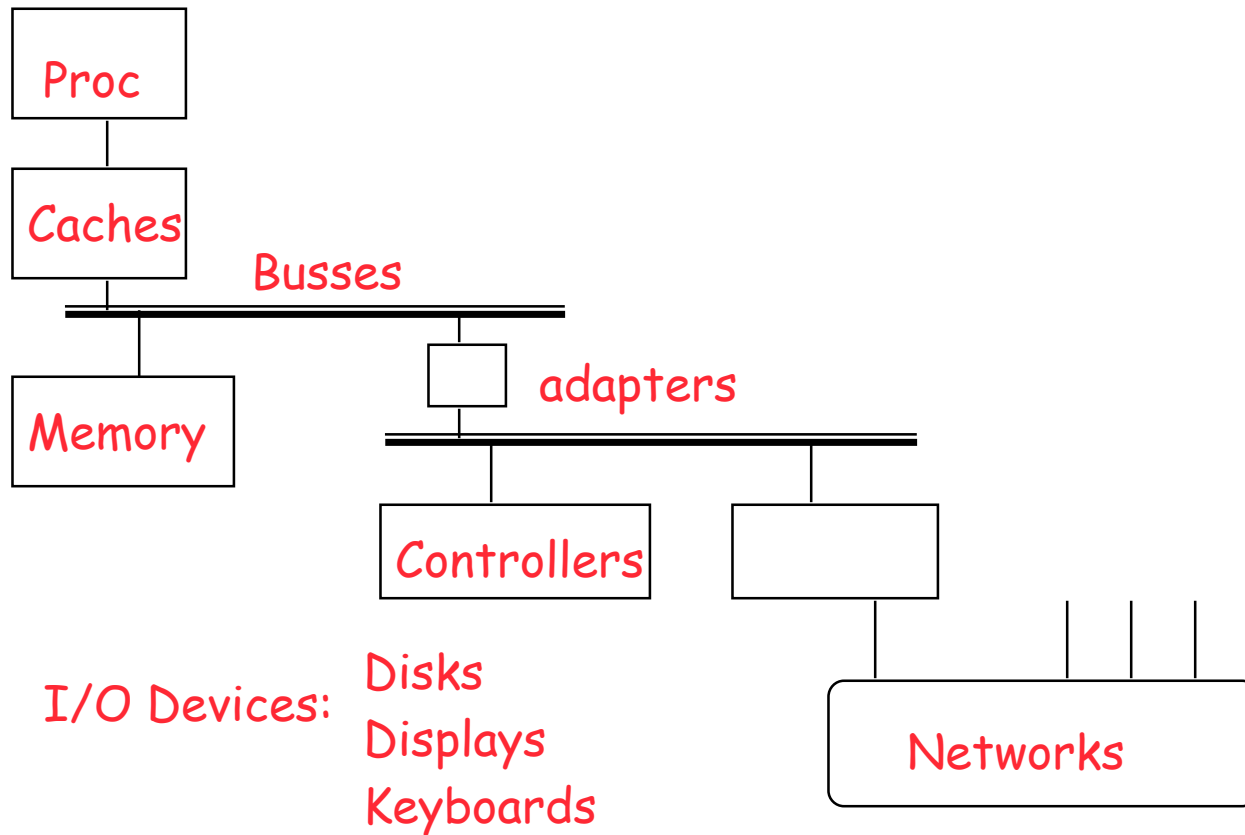
## Busses & controllers to connect processor, memory, IO devices



MIT Whirlwind, 1951

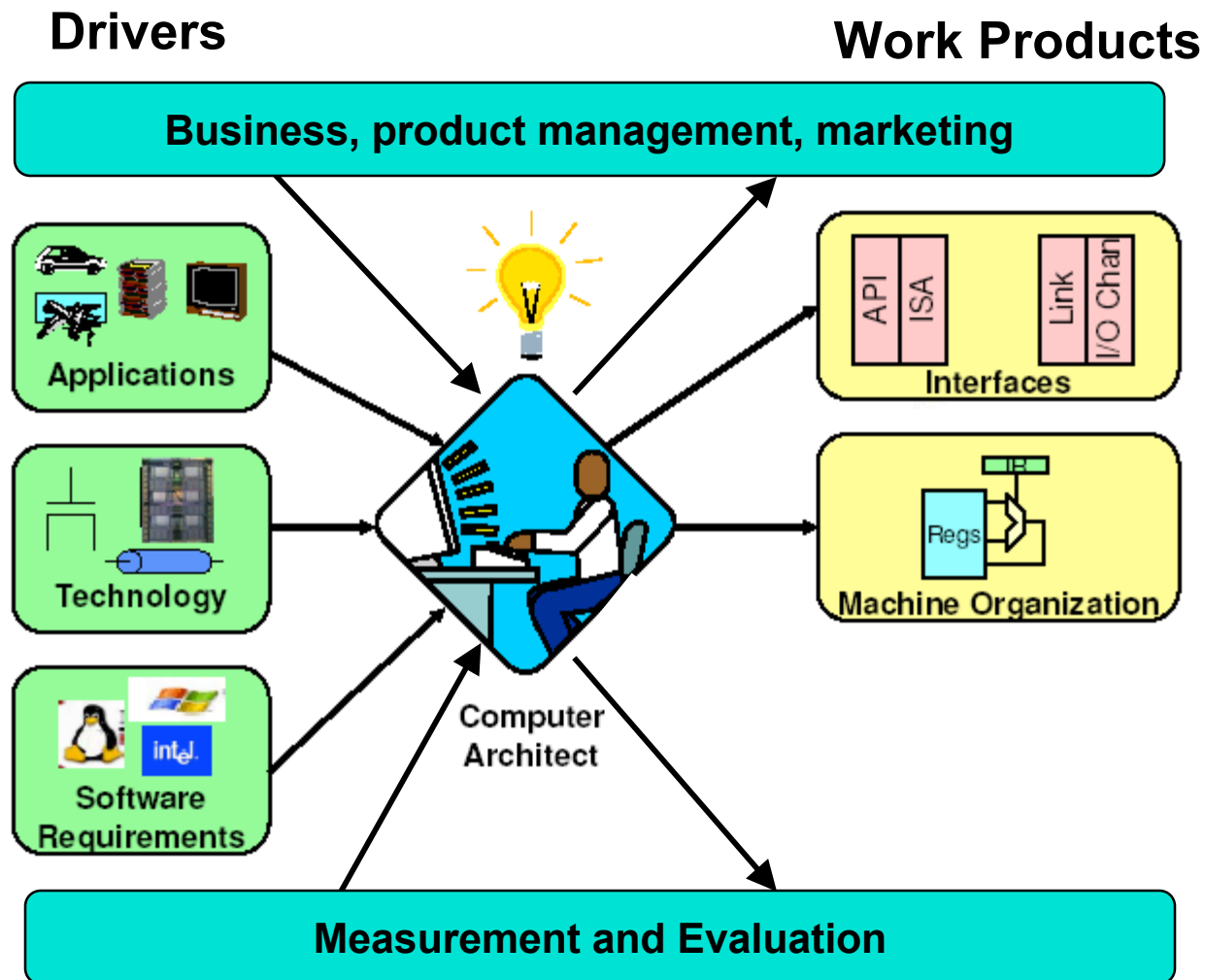
Computers are pervasive - servers, standalone PCs, network processors, embedded processors, ...

# Today, “Computers” are Connected Processors



All have interfaces & organizations

# What does a computer architect do?



Translates business and technology drives  
into efficient systems for computing tasks.

# Metrics of Efficiency - Examples

## Desktop computing

- Examples: PCs, workstations
- Metrics: performance (latency), cost, time to market

## Server computing

- Examples: web servers, transaction servers, file servers
- Metrics: performance (throughput), reliability, scalability

## Embedded computing

- Examples: microwave, printer, cell phone, video console
- Metrics: performance (real-time), cost, power consumption, complexity

# Applications Drive Design Points

## Numerical simulations

- Floating-point performance
- Main memory bandwidth

## Transaction processing

- I/Os per second and memory bandwidth
- Integer CPU performance

## Media processing

- Repeated low-precision 'pixel' arithmetic
- Multiply-accumulate rates
- Bit manipulation

## Embedded control

- I/O timing
- Real-time behavior



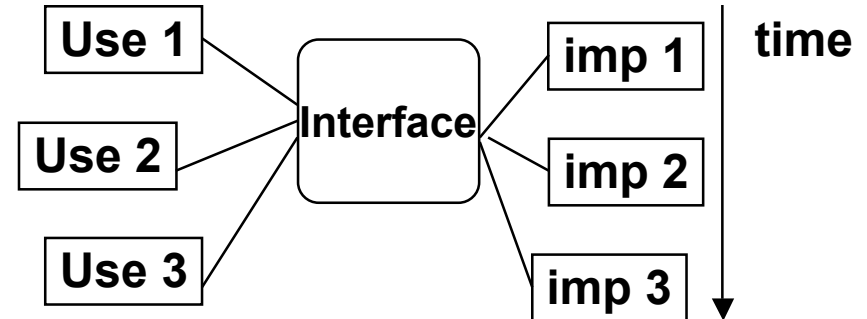
Architecture decisions will often exploit application behavior

# Characteristics of a Good Interface Design

Well defined for users and implementers

## Interoperability (Hardware) / Compatibility (Software)

- Lasts through multiple implementations across multiple technologies (portability, compatibility)
- Efficiently supports multiple implementations
  - Competitive market
  - Compatible at multiple cost / performance design points



## IP Investment Preservation

- Extensible function grows from a stable base
- Generality of application permits reuse of training, tools and implementations

Interface usage can far exceed the most optimistic projections of it's designer:

## Applies to many types of interfaces

- Instruction set architectures
  - S/360 1964 ~ present
  - X86 1972 ~ present
  - SPARC 1981 ~ present
- Network protocols
  - Ethernet 1973 ~ present
  - TCP/IP 1974 ~ present
- Programming languages
  - C 1973 ~ present

# Course Structure



# What You Need to Know from prerequisites

Basic machine structure

- Processor, memory, I/O

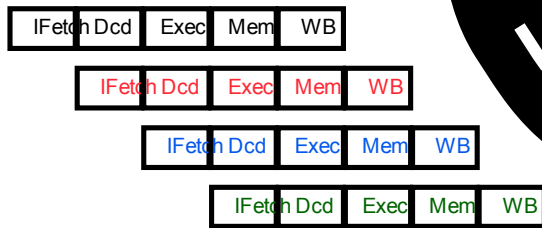
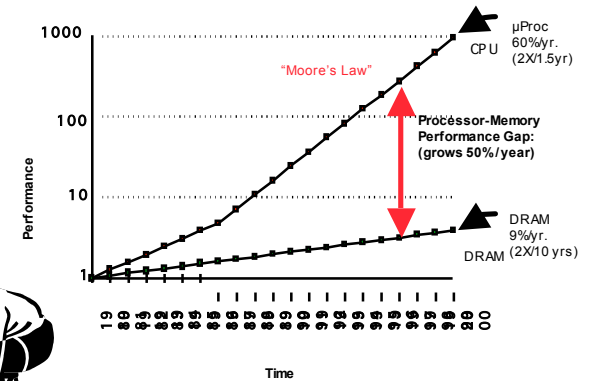
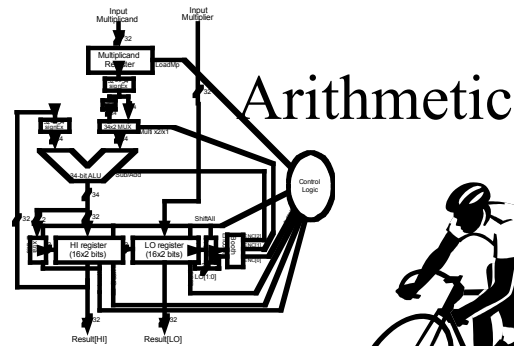
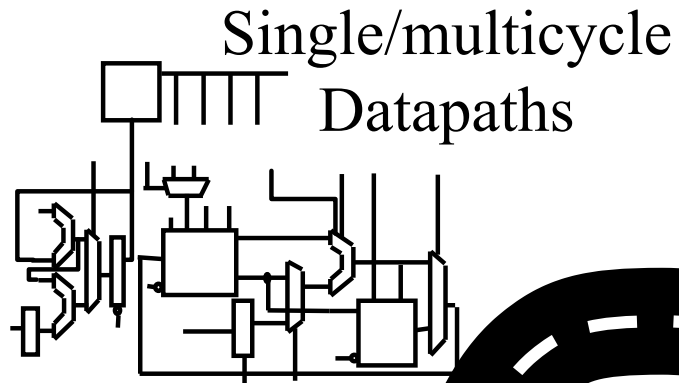
Assembly language programming

Simple operating system concepts

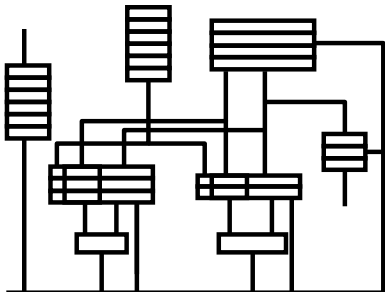
Logic design

- Logical equations, schematic diagrams, FSMs, Digital design

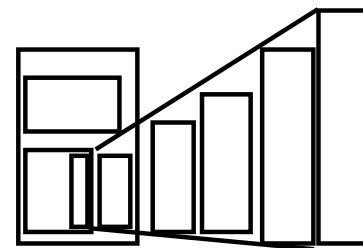
# Roadmap



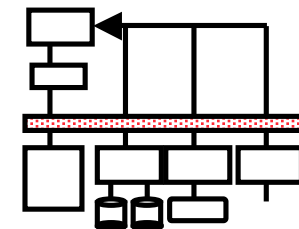
Pipelining



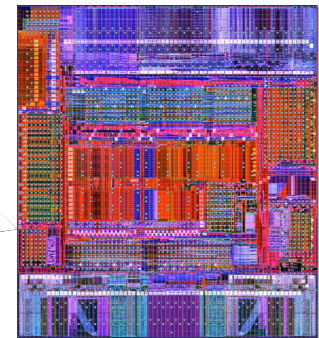
ECE 361



Memory Systems



I/O



# Course Basics

## Website

- [www.ece.northwestern.edu/~choudhar/361/index.htm](http://www.ece.northwestern.edu/~choudhar/361/index.htm)
- Check regularly for announcements
- All course materials posted -- lecture notes, homework, labs, supplemental materials
- Communicate information, questions and issues

Office Hours - Tech L469 - Tuesday 3-4pm (or by appointment)

Text supplements lectures and assigned reading should be done prior to lectures. I assume that all assigned readings are completed even if the material is not covered in class.

## Homework, Labs and Exams

- Collaborative study and discussion is highly encouraged
- Work submitted must be your own
- Individual grade

## Project

- Collaborative effort
- Team grade

# Grade

## 35% Homework and Labs

- 4 homework sets
- Lab - individual grade,
  - ALU

## 30% Team Project

- MIPS subset
- Design and CAD intensive effort

## 35% Late midterm Exam (Nov 16)

- Open book, open notes

# Project

Teams of 3-4 students

You will be required to

- Use advanced CAD tools - Mentor Graphics
- Design a simple processor (structural design and implementation) - MIPS subset
- Validate correctness using sample programs of your own and provided as part of the assignment

Written presentation submitted (due Dec 3, 2004)

You may also use VHDL (structural) to design your system if you know VHDL sufficiently well

# Course Structure

## Lectures:

- 1 week on Overview and Introduction (Chap 1 and 2)
- 2 weeks on ISA Design
- 4 weeks on Proc. Design
- 2 weeks on Memory and I/O

Reading assignments posted on the web for each week. Please read the appropriate material before the class.

Note that the above is approximate

Copy of all lecture notes available from the department for a charge (bound nicely)

# Technology Drivers

# Technology Drives Advances in Computer Design

- Evolution      Each level of abstraction is continually trying to improve
- Disruption    Fundamental economics or capability cross a major threshold



## Significant technology disruptions

Logic      Relays → Vacuum tubes →  
single transistors →  
SSI/MSI (TTL/ECL) → VLSI (MOS)

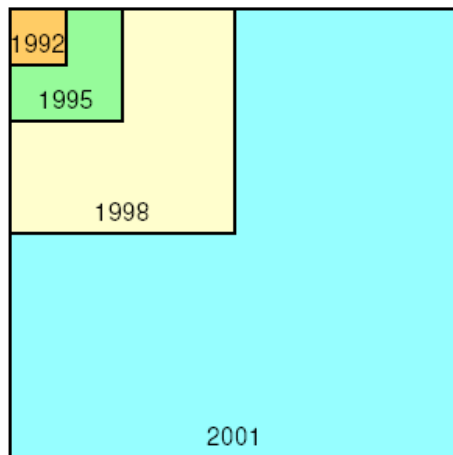
Registers      Delay lines → drum → semiconductor

Memory      Delay lines → magnetic drum → core  
→ SRAM → DRAM

External Storage      Paper tape → Paper cards →  
magnetic drum →  
magnetic disk

Today, technology is driven by semiconductor and magnetic disk technology. What are the the next technology shifts?

# Semiconductor and Magnetic Disk Technologies Have Sustained Dramatic Yearly Improvement since 1975

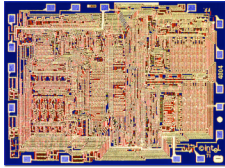


64x more devices since 1992  
4x faster devices

**Moore's "Law"** - The observation made in 1965 by Gordon Moore, co-founder of Intel, that the number of transistors per square inch on integrated circuits had doubled every year since the integrated circuit was invented. Moore predicted that this trend would continue for the foreseeable future. In subsequent years, the pace slowed down a bit, but ***data density has doubled approximately every 18 months***, and this is the current definition of Moore's Law, which Moore himself has blessed. Most experts, including Moore himself, expect Moore's Law to hold for at least another two decades.

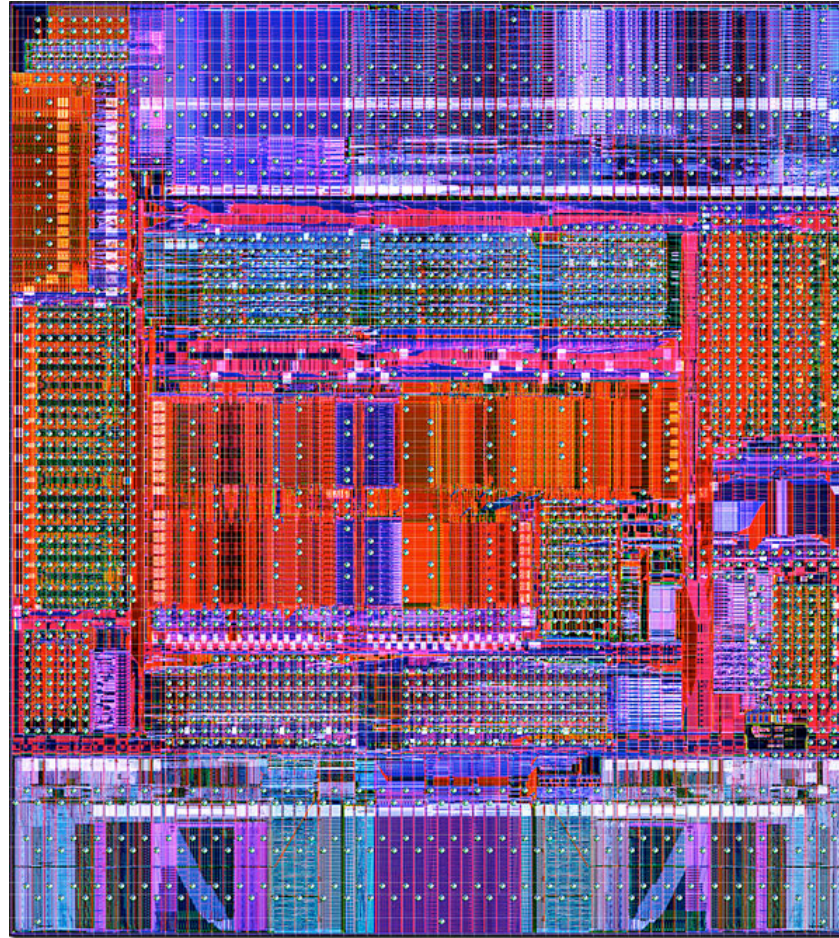
	Capacity	Speed	Cost
Logic	60%	40%	25%
Clock Rate		20%	
DRAM	60%	7%	25%
Disk	60%	3%	25%
Network		40%	25%

# Device Density Increases Faster Than Die Size



**1971**

Intel 4004 was a 3 chip set with a 2kbit ROM chip, a 320bit RAM chip and the 4bit processor each housed in a 16 pin DIP package. The 4004 processor required roughly 2,300 transistors to implement, used a silicon gate PMOS process with 10 $\mu$ m linewidths, had a 108KHz clock speed and a die size of 13.5mm<sup>2</sup>. Designer - Ted Hoff.



**1996**

HP PA8000 -  
17.68mmx19.1mm,  
3.8M transistors.

	<u>i4004</u>	<u>PA9000</u>	<u>Factor</u>	<u>Yearly Improvement</u>
Area (mm)	13.5	338	1:25	14%
Transistors	2300	3,800,000	1:1652	34%

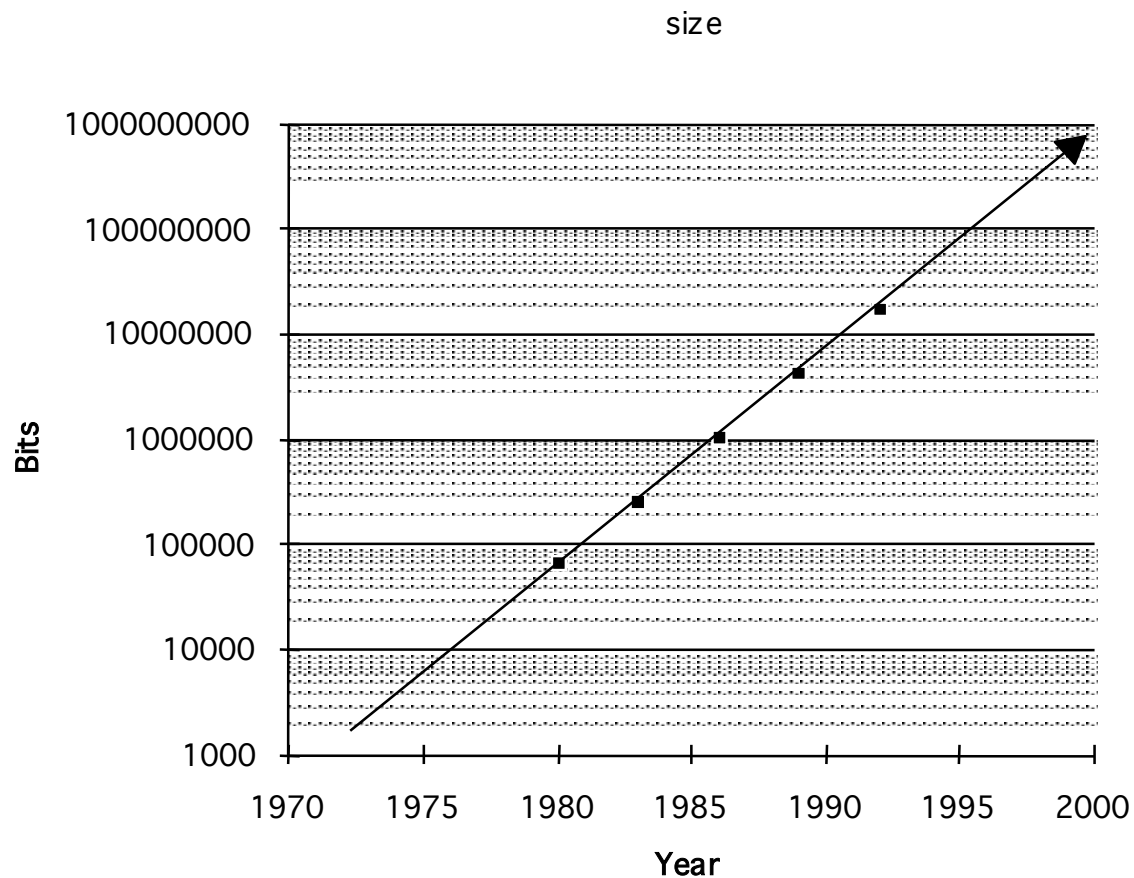
Source: <http://micro.magnet.fsu.edu/chipshots/>

## Example: Intel Semiconductor Roadmap

Process	P856	P858	Px60	P1262	P1264	P1266
1st Production	1997	1999	2001	2003	2005	2007
Lithography	0.25um	0.18um	0.13um	90nm	65nm	45nm
Gate Length	0.20um	0.13um	<70nm	<50nm	<35nm	<25nm
Wafer Diameter (mm)	200	200	200/300	300	300	300

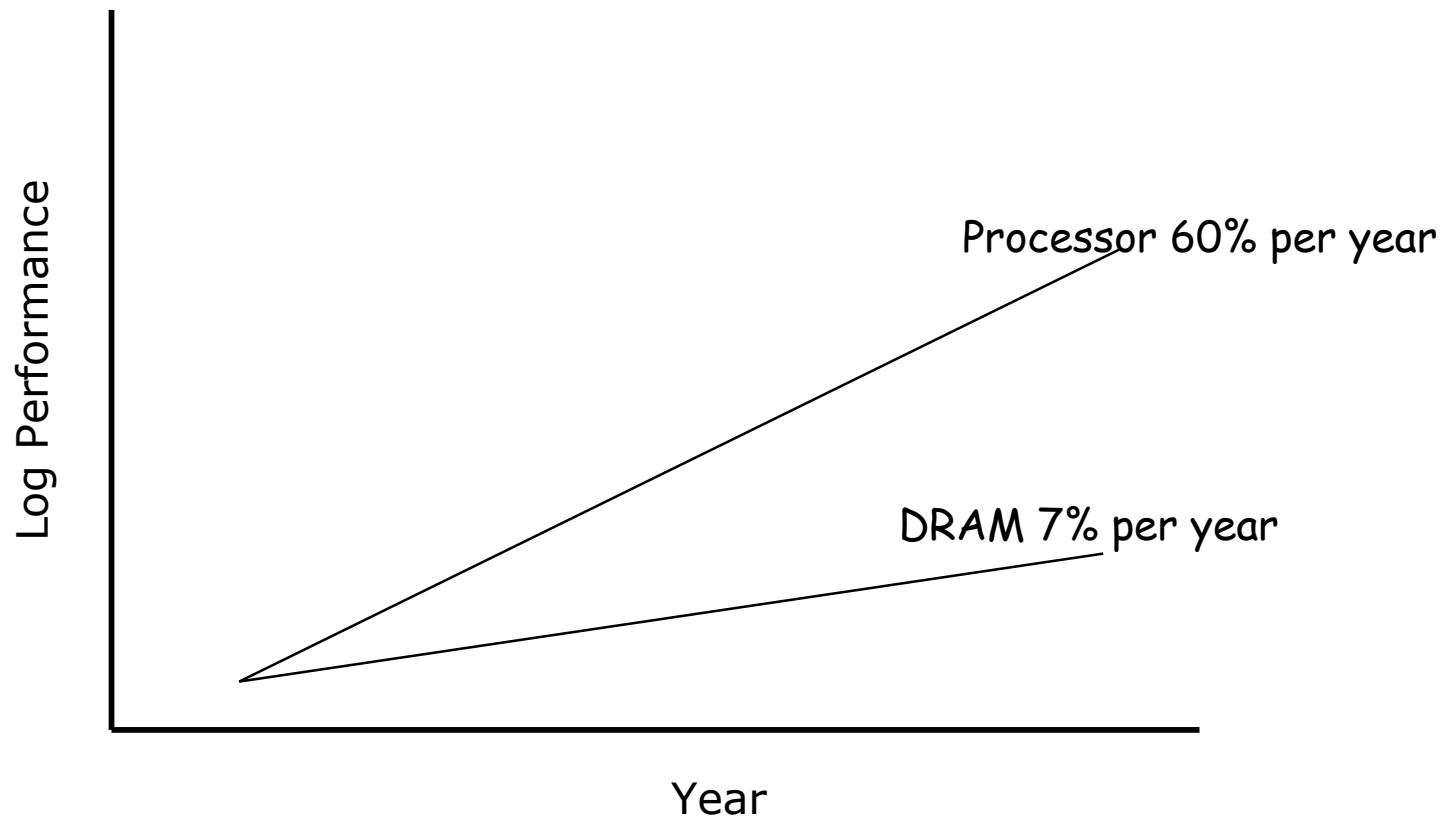
Source: Mark Bohr, Intel, 2002

# DRAM Drives the Semiconductor Industry



Year	Capacity	Access
1980	64 Kb	250 ns
1983	256 Kb	220 ns
1986	1 Mb	190 ns
1989	4 Mb	165 ns
1992	16 Mb	145 ns
1996	64 Mb	120 ns
1999	256 Mb	100 ns
2002	1Gb	80 ns

## Memory Wall: Speed Gap between Processor and DRAM



Source: Junji Ogawa, Stanford

The divergence between performance and cost drives the need for memory hierarchies, to be discussed in future lectures.

# Semiconductor evolution drives improved designs

## 1970s

- Multi-chip CPUs
- Semiconductor memory very expensive
- Complex instruction sets (good code density)
- Microcoded control

## 1980s

- 5K - 500 K transistors
- Single-chip CPUs
- RAM is cost-effective
- Simple, hard-wired control
- Simple instruction sets
- Small on-chip caches

## 1990s

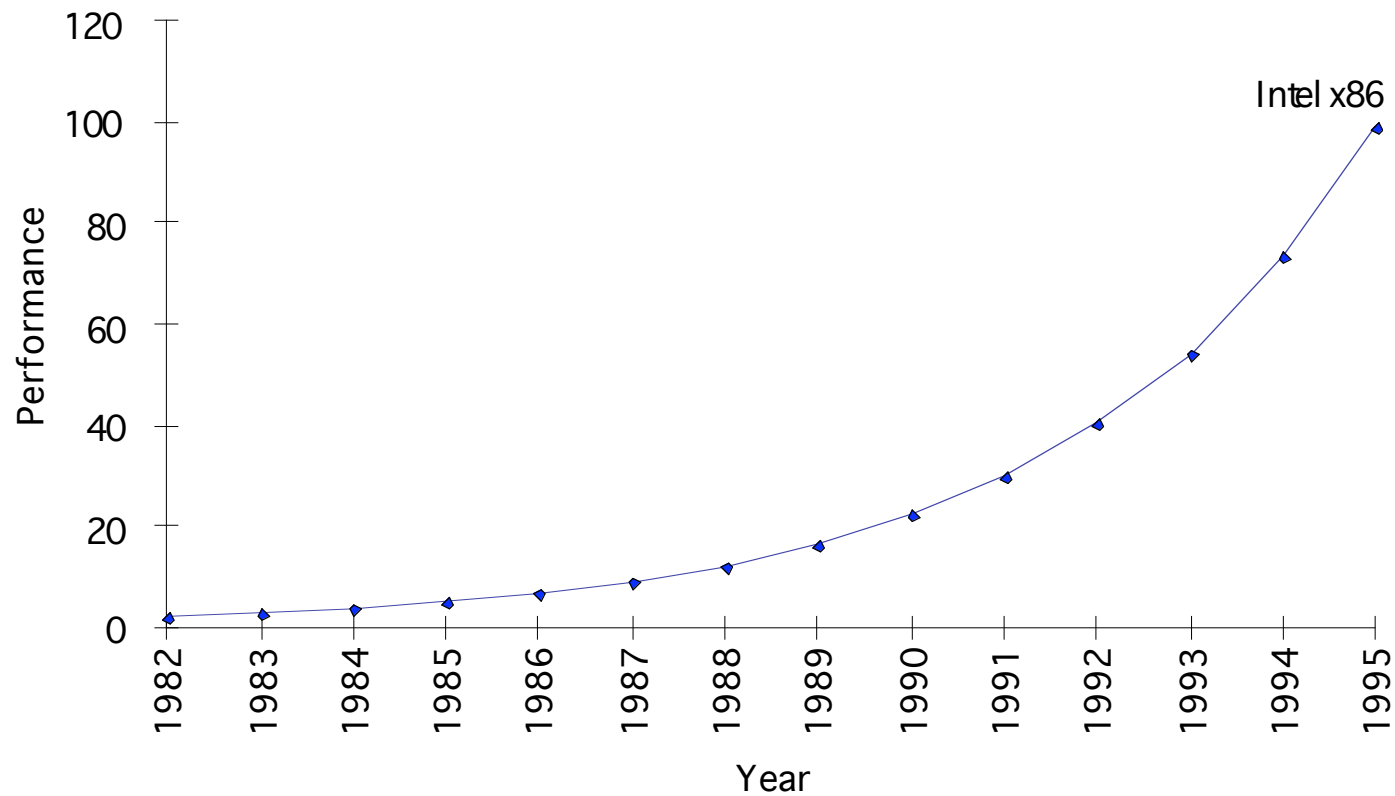
- 1 M - 64M transistors
- Complex control to exploit instruction-level parallelism
- Super deep pipelines

## 2000s

- 100 M - 5 B transistors
- Slow wires
- Power consumption
- Design complexity

Note: Gate speeds and power/cooling also improved

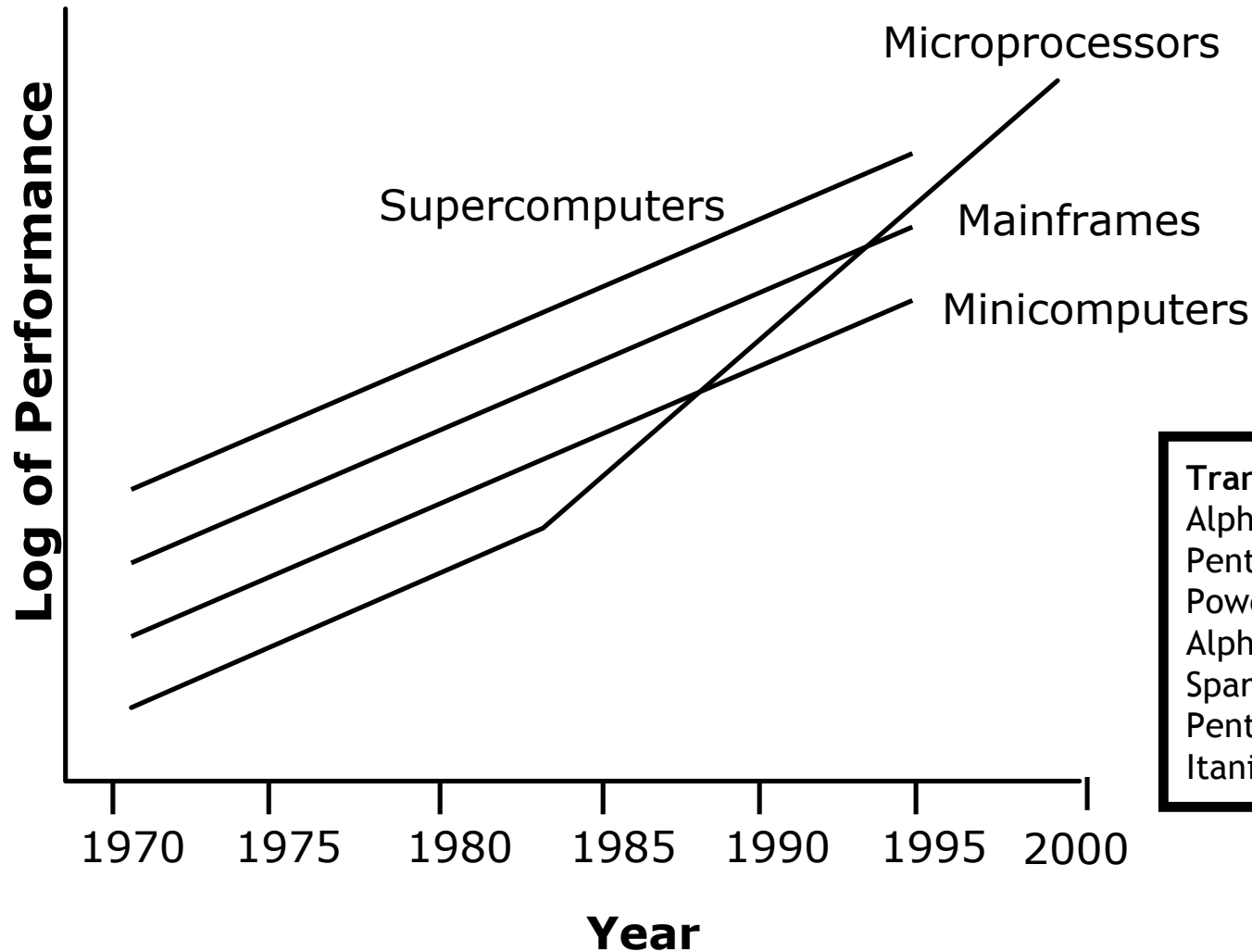
## Processor Performance (SPEC)



System performance improves 50% per year. More about SPEC in a future lecture.



# Technology drives industry disruption and creates opportunity



## Transistors

Alpha 21264: 15 million  
Pentium Pro: 5.5 million  
PowerPC 620: 6.9 million  
Alpha 21164: 9.3 million  
Sparc Ultra: 5.2 million  
Pentium 4: 42 million  
Itanium: 220 million

# 危機

# Why Such Change in 10 years?

## Performance

- Technology Advances
  - CMOS VLSI dominates older technologies (TTL, ECL) in cost and performance
- Computer architecture advances improves low-end
  - RISC, superscalar, RAID, ...

## Price: Lower costs due to ...

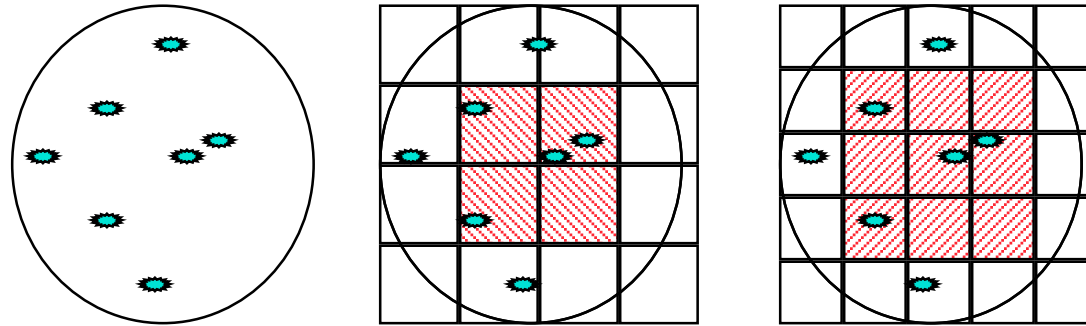
- Simpler development
  - CMOS VLSI: smaller systems, fewer components
- Higher volumes
  - CMOS VLSI : same dev. cost 1,000 vs. 100,000,000 units
- Lower margins by class of computer, due to fewer services

## Function

- Rise of networking / local interconnection technology

# Cost and Price

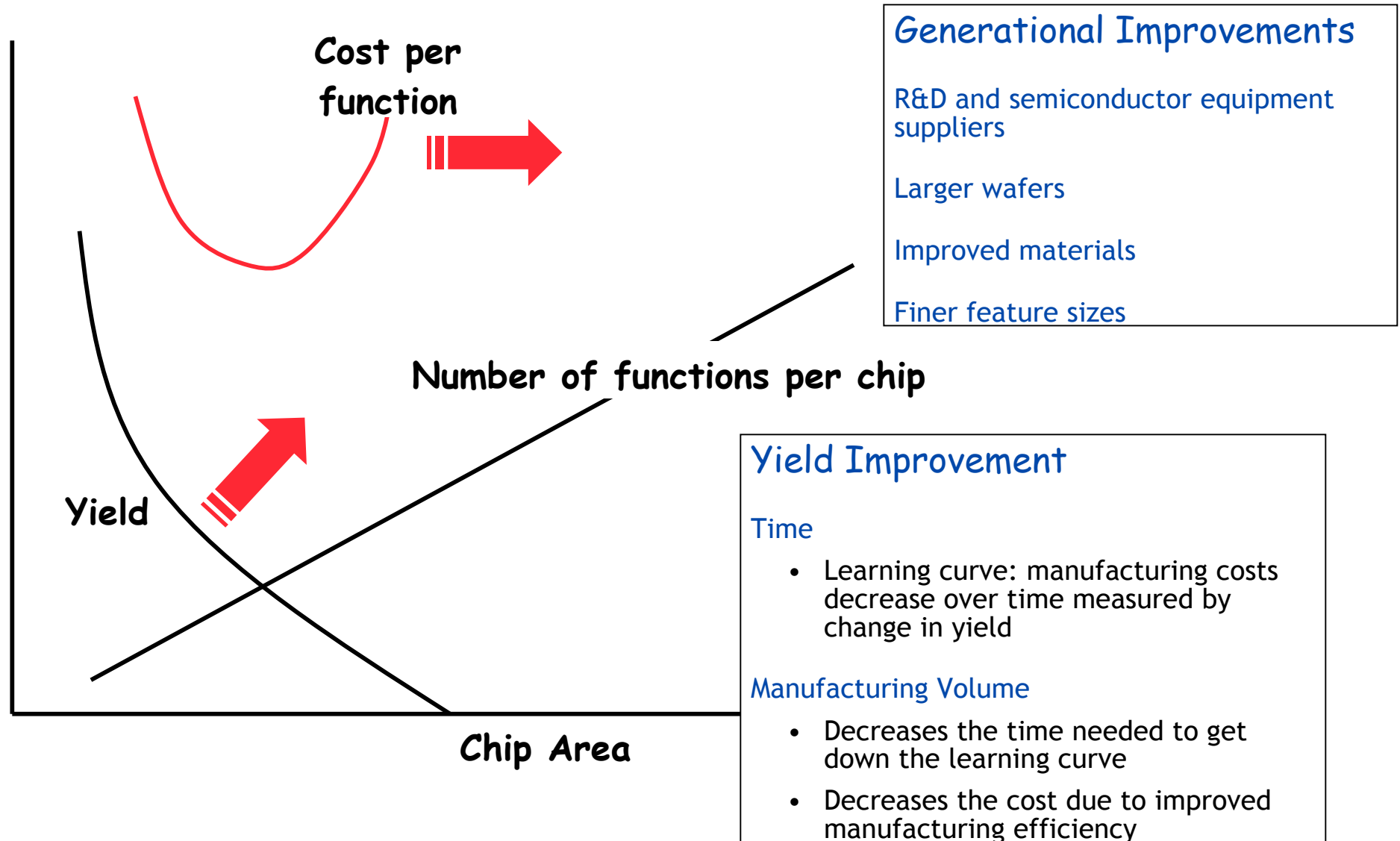
# Integrated Circuit Manufacturing Costs



$$\text{Die Cost} = \frac{\text{Wafer Cost}}{\text{Dies per Wafer} \times \text{Die Yield}}$$

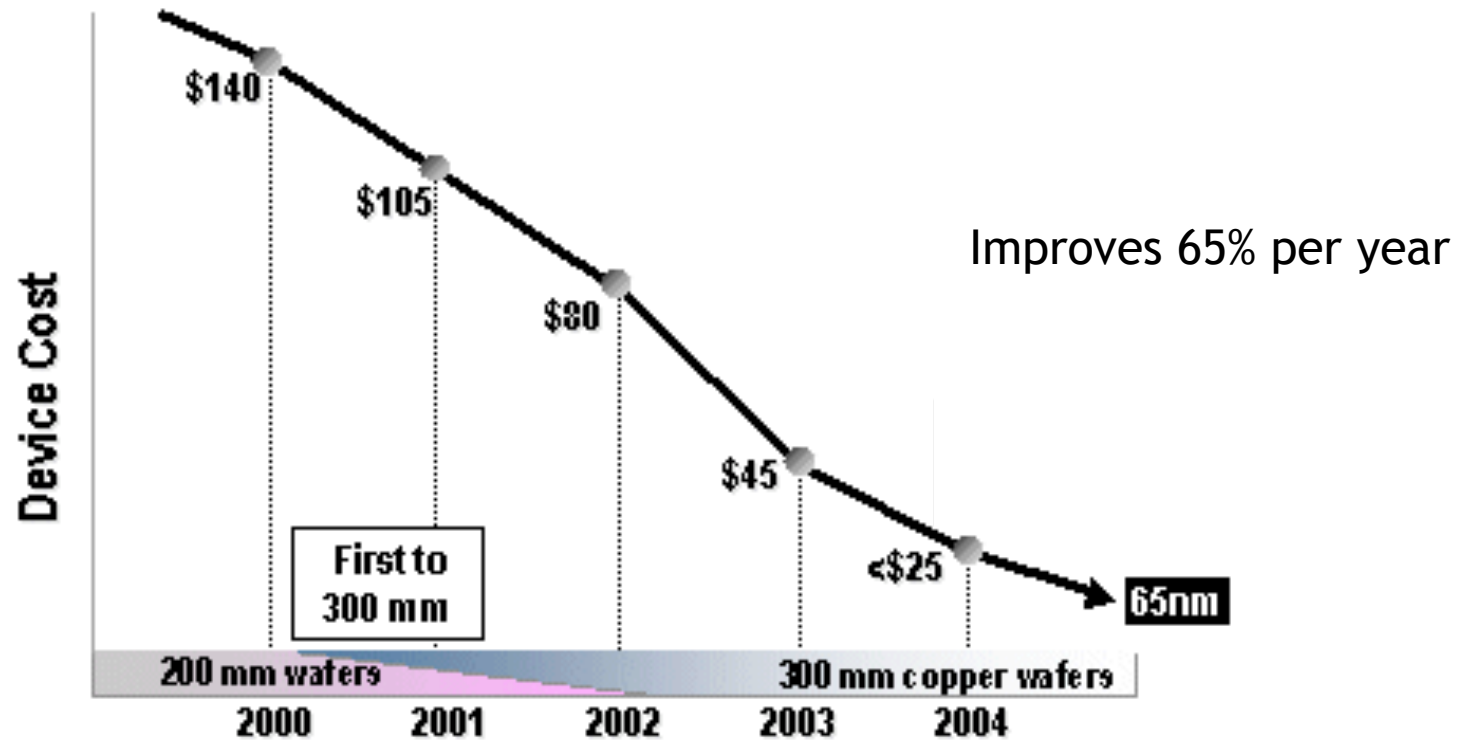
IC yield is a largely a function of defect density.  
Yield curves improve over time with manufacturing experience.

# Relationship of complexity, cost and yield




Source: The History of the Microcomputer - Invention and Evolution, Stan Mazor

## Example: FPGA Cost per 1M Gates



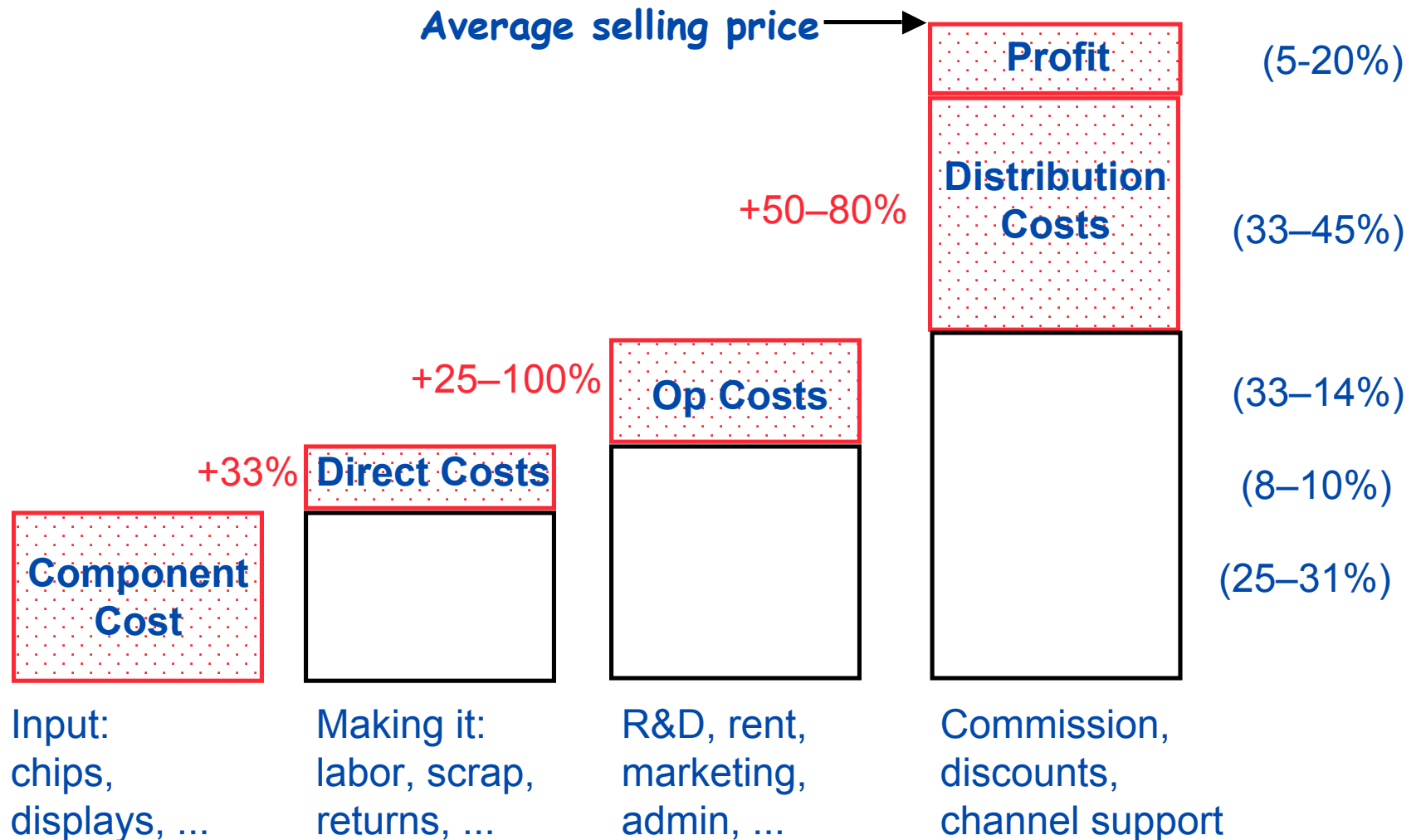
Source: Xilinx

# System Cost Example: Web Server

	<u>System total cost</u>	<u>Subsystem</u>	<u>% of</u>
	Cabinet	Sheet metal,	1%
	plastic	Power supply,	2%
	fans	Cables, nuts,	1%
	bolts		
	(Subtotal)		(4%)
	Motherboard		20%
	Processor		20%
		DRAM	20%
		I/O	10%
	system		
	interface	Network	4%
	board	Printed Circuit	1%
		(Subtotal)	
	(60%)		

Picture: <http://developer.intel.com/design/servers/sr1300/>

## Example: Cost vs Price





# Summary

## Computer Design

- Levels of abstraction
- Instruction sets and computer architecture

## Architecture design process

## Interfaces

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## Course Structure

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## Technology as an architectural driver

- Evolution of semiconductor and magnetic disk technology
  - New technologies replace old
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## Cost and Price

- Semiconductor economics